## PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Colgan, et al. Examiner: Mitchell, James M.

**Serial No.:** 10/789,500 **Group:** Art Unit 2813

**Filed:** February 27, 2004 **Docket:** YOR920030527US1 (8728-665)

For: APPARATUS AND METHODS FOR COOLING

SEMICONDUCTOR INTEGRATED CIRCUIT PACKAGE STRUCTURES

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313

## RESPONSE

This is a response to the Office Communication of October 17, 2006, noting Applicants' failure to submit drawings as requested by the Examiner in the Office Action mailed on April 21, 2006, notwithstanding Applicants' bona fide objection and traversal of the drawing objections as set forth in Applicants Amendment filed on July 25, 2006. The Office Communication indicates that the response period will not be restarted and that failure to timely and appropriately respond to the Communication will result in abandonment of the application.

In the interest of cooperation and expediting prosecution, Applicants will submit one or more additional drawings to address the drawing objections set forth in the Office Action of April 21, 2006. However, given the short notice of Applicant's purported non-compliance with the drawing request set forth in the Office Action of 4/21/06 and imminent abandon date (where the application technically becomes abandoned on 10/21/06), Applicants respectfully request that the Examiner allow a reasonable period of time (such as 30 days) from the mailing date of the Communication to prepare the drawings that are needed to comply with the Examiner's request.

Respectfully submitted,

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